24AA08/24LC08B

8K I²C™ Serial EEPROM

Device Selection Table

| Part Number	Vcc Range	Max Clock Frequency	Temp Ranges
24AA08	1.8-5.5	400 kHz[1]	I
24LC08B	2.5-5.5	400 kHz	I, E

Note 1: 100 kHz for Vcc <2.5V

Features

- Single supply with operation down to 1.8V
- Low power CMOS technology
  - 1 mA active current typical
  - 1 µA standby current typical (I-temp)
- Organized as 4 blocks of 256 bytes (4 x 256 x 8)
- 2-wire serial interface bus, I²C™ compatible
- Schmitt Trigger inputs for noise suppression
- Output slope control to eliminate ground bounce
- 100 kHz (<2.5V) and 400 kHz (≥2.5V) compatibility
- Self-timed write cycle (including auto-erase)
- Page write buffer for up to 16 bytes
- 2 ms typical write cycle time for page write
- Hardware write protect for entire memory
- Can be operated as a serial ROM
- Factory programming (QTP) available
- ESD protection > 4,000V
- 1,000,000 erase/write cycles
- Data retention > 200 years
- 8-lead PDIP, SOIC, TSSOP and MSOP packages
- 5-lead SOT-23 package
- Standard and Pb-free finishes available
- Available for extended temperature ranges:
  - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C

Description

The Microchip Technology Inc. 24AA08/24LC08B (24XX08*) is a 8 Kbit Electrically Erasable PROM. The device is organized as four blocks of 256 x 8-bit memory with a 2-wire serial interface. Low voltage design permits operation down to 1.8V, with standby and active currents of only 1 µA and 1 mA, respectively. The 24XX08 also has a page write capability for up to 16 bytes of data. The 24XX08 is available in the standard 8-pin PDIP, surface mount SOIC, TSSOP and MSOP packages and is also available in the 5-lead SOT-23 package.

Package Types

Note: Pins A0, A1 and A2 are not used by the 24XX08. (No internal connections).
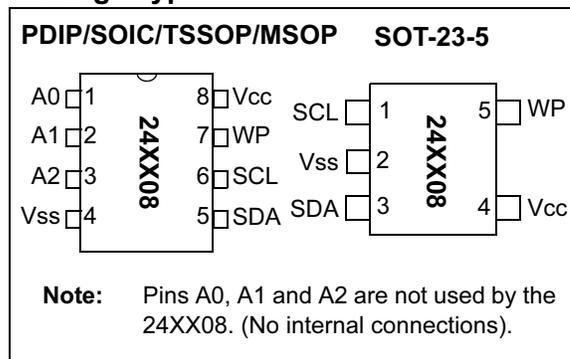
Block Diagram
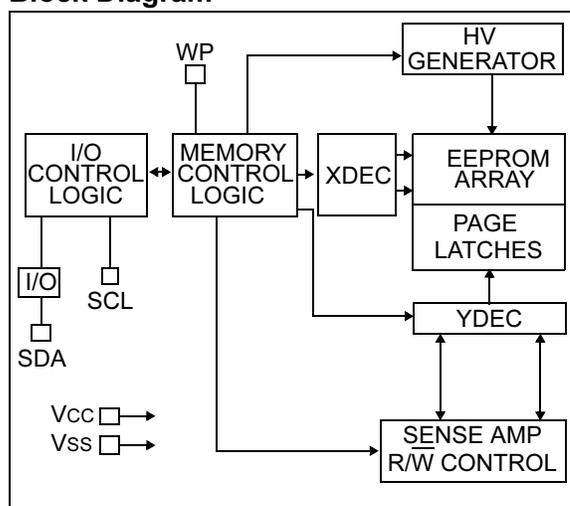
*24XX08 is used in this document as a generic part number for the 24AA08/24LC08B devices.

24AA08/24LC08B

1.0   ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings [†]

V_{CC}..6.5V

All inputs and outputs w.r.t. V_{SS} .... -0.3V to V_{CC} +1.0V

Storage temperature ....-65°C to +150°C

Ambient temperature with power applied...-65°C to +125°C

ESD protection on all pins ....≥ 4 kV

> † NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

1.1   DC Characteristics

DC CHARACTERISTICS			V_{CC} = +1.8V to +5.5V Industrial (I): T_{AMB} = -40°C to +85°C Automotive (E): T_{AMB} = -40°C to +125°C				
Param. No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
D1	V_{IH}	**WP, SCL and SDA pins**	—	—	—	—	—
D2	—	High level input voltage	0.7 V_{CC}	—	—	V	—
D3	V_{IL}	Low level input voltage	—	—	0.3 V_{CC}	V	—
D4	V_{HYS}	Hysteresis of Schmitt trigger inputs	0.05 V_{CC}	—	—	V	**(Note)**
D5	V_{OL}	Low level output voltage	—	—	0.40	V	I_{OL} = 3.0 mA, V_{CC} = 2.5V
D6	I_{LI}	**Input leakage current**	—	—	±10	µA	V_{IN} =.1V to V_{CC}
D7	I_{LO}	**Output leakage current**	—	—	±10	µA	V_{OUT} =.1V to V_{CC}
D8	C_{IN}, C_{OUT}	Pin capacitance (all inputs/outputs)	—	—	10	pF	V_{CC} = 5.0V **(Note)** T_{AMB} = 25°C, F_{CLK} = 1 MHz
D9	I_{CC} write	**Operating current**	—	0.1	3	mA	V_{CC} = 5.5V, SCL = 400 kHz
D10	I_{CC} read		—	0.05	1	mA	—
D11	I_{CCS}	**Standby current**	—	0.01	1	µA	Industrial
			—	—	5	µA	Automotive SDA = SCL = V_{CC} WP = V_{SS}

Note: This parameter is periodically sampled and not 100% tested.

1.2   AC Characteristics

AC CHARACTERISTICS			Vcc = +1.8V to +5.5V Industrial (I): TAMB = -40°C to +85°C Automotive (E): TAMB = -40°C to +125°C				
Param. No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
1	FCLK	Clock frequency	— —	— —	400 100	kHz	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
2	THIGH	Clock high time	600 4000	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
3	TLOW	Clock low time	1300 4700	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
4	TR	SDA and SCL rise time **(Note 1)**	— —	— —	300 1000	ns	2.5V ≤ Vcc ≤ 5.5V **(Note 1)** 1.8V ≤ Vcc < 2.5V **(24AA08)** **(Note 1)**
5	TF	SDA and SCL fall time	— —	— —	300 	ns	**(Note 1)**
6	THD:STA	START condition hold time	600 4000	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
7	TSU:STA	START condition setup time	600 4700	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
8	THD:DAT	Data input hold time	0 	— —	— —	ns	**(Note 2)**
9	TSU:DAT	Data input setup time	100 250	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
10	TSU:STO	STOP condition setup time	600 4000	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
11	TAA	Output valid from clock **(Note 2)**	— —	— —	900 3500	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
12	TBUF	Bus free time: Time the bus must be free before a new transmission can start	1300 4700	— —	— —	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
13	TOF	Output fall time from VIH minimum to VIL maximum	20+0.1CB —	— —	250 250	ns	2.5V ≤ Vcc ≤ 5.5V 1.8V ≤ Vcc < 2.5V **(24AA08)**
14	TSP	Input filter spike suppression (SDA and SCL pins)	—	—	50	ns	**(Notes 1 and 3)**
15	TWC	Write cycle time (byte or page)	—	—	5	ms	—
16	—	Endurance	1M	—	—	cycles	25°C, **(Note 4)**

Note 1:   Not 100% tested. CB = total capacitance of one bus line in pF.

2:   As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

3:   The combined TSP and VHYS specifications are due to new Schmitt Trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

4:   This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained on Microchip's web site: www.microchip.com.

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**FIGURE 1-1:** **BUS TIMING DATA**
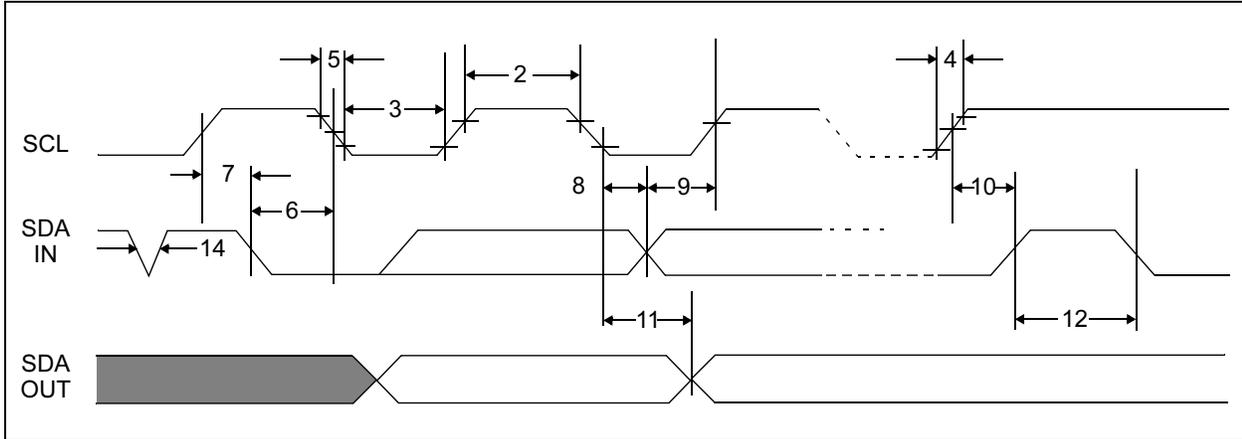
FIGURE 1-2: **BUS TIMING START/STOP**
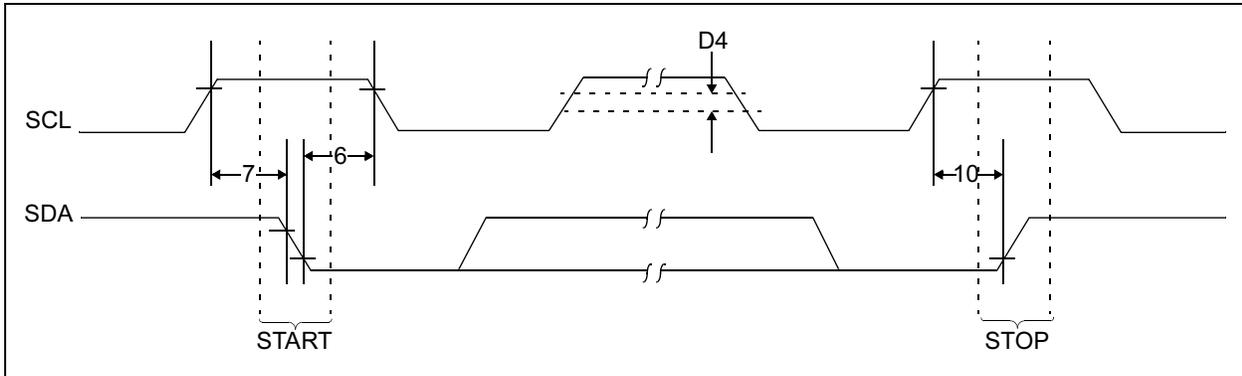
2.0   FUNCTIONAL DESCRIPTION

The 24XX08 supports a bi-directional, 2-wire bus and data transmission protocol. A device that sends data onto the bus is defined as a transmitter, while a device receiving data is defined as a receiver. The bus has to be controlled by a master device which generates the serial clock (SCL), controls the bus access and generates the START and STOP conditions, while the 24XX08 works as slave. Both master and slave can operate as transmitter or receiver, but the master device determines which mode is activated.

3.0   BUS CHARACTERISTICS

The following **bus protocol** has been defined:

• Data transfer may be initiated only when the bus is not busy.
• During data transfer, the data line must remain stable whenever the clock line is HIGH. Changes in the data line while the clock line is HIGH will be interpreted as a START or STOP condition.

Accordingly, the following bus conditions have been defined (Figure 3-1).

3.1   Bus not Busy (A)

Both data and clock lines remain HIGH.

3.2   Start Data Transfer (B)

A HIGH-to-LOW transition of the SDA line while the clock (SCL) is HIGH determines a START condition. All commands must be preceded by a START condition.

3.3   Stop Data Transfer (C)

A LOW-to-HIGH transition of the SDA line while the clock (SCL) is HIGH determines a STOP condition. All operations must be ended with a STOP condition.

3.4   Data Valid (D)

The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the HIGH period of the clock signal.

The data on the line must be changed during the LOW period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of the data bytes transferred between the START and STOP conditions is determined by the master device and is theoretically unlimited, although only the last sixteen will be stored when doing a write operation. When an overwrite does occur it will replace data in a first-in first-out (FIFO) fashion.

3.5   Acknowledge

Each receiving device, when addressed, is obliged to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse which is associated with this Acknowledge bit.

> **Note:**   The 24XX08 does not generate any Acknowledge bits if an internal programming cycle is in progress.

The device that acknowledges, has to pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. During reads, a master must signal an end of data to the slave by not generating an Acknowledge bit on the last byte that has been clocked out of the slave. In this case, the slave (24XX08) will leave the data line HIGH to enable the master to generate the STOP condition.

**FIGURE 3-1:   DATA TRANSFER SEQUENCE ON THE SERIAL BUS**
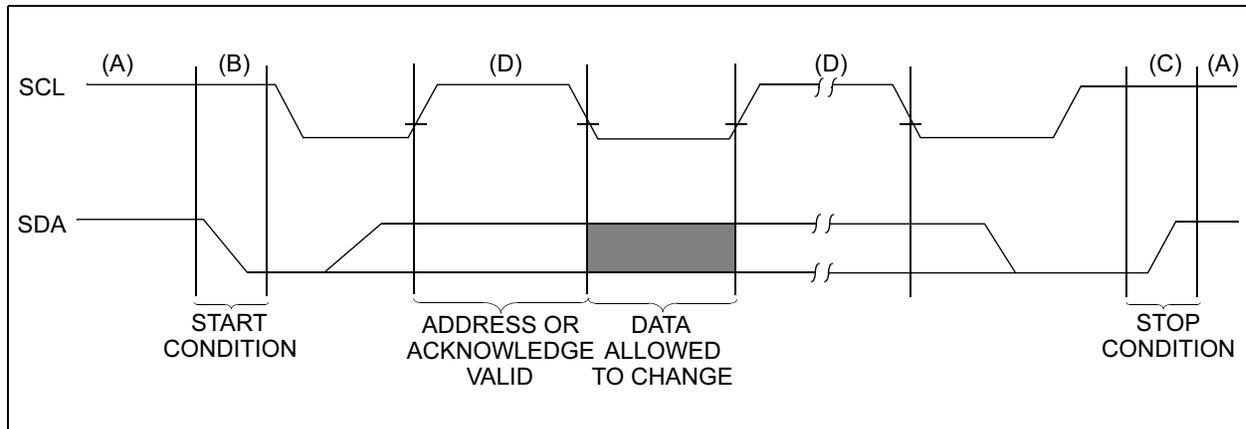
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3.6   Device Addressing

A control byte is the first byte received following the START condition from the master device (Figure 3-1). The control byte consists of a four-bit control code. For the 24XX08,this is set as `1010` binary for read and write operations. The next three bits of the control byte are the block-select bits (B2, B1, B0). B2 is a 'don't care' for the 24XX08. They are used by the master device to select which of the four 256 word-blocks of memory are to be accessed. These bits are in effect the three Most Significant bits of the word address.

The last bit of the control byte defines the operation to be performed. When set to '1', a read operation is selected. When set to '0' a write operation is selected. Following the START condition, the 24XX08 monitors the SDA bus checking the device type identifier being transmitted and, upon receiving a `1010` code, the slave device outputs an Acknowledge signal on the SDA line. Depending on the state of the R/$\overline{W}$ bit, the 24XX08 will select a read or write operation.

Operation	Control Code	Block Select	R/$\overline{W}$
Read	`1010`	Block Address	`1`
Write	`1010`	Block Address	`0`

**FIGURE 3-1:   CONTROL BYTE ALLOCATION**

X = 'Don't care'
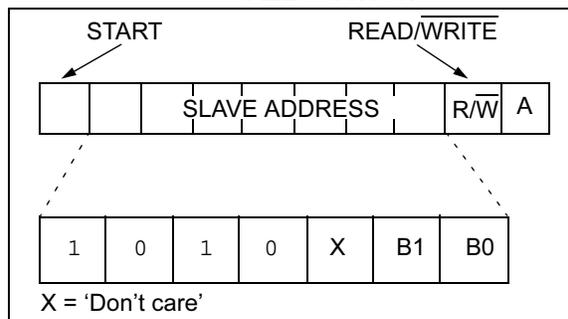
4.0   WRITE OPERATION

4.1   Byte Write

Following the START condition from the master, the device code (4 bits), the block address (3 bits) and the R/$\overline{W}$ bit, which is a logic-LOW, is placed onto the bus by the master transmitter. This indicates to the addressed slave receiver that a byte with a word address will follow once it has generated an Acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the master is the word address and will be written into the address pointer of the 24XX08. After receiving another Acknowledge signal from the 24XX08, the master device will transmit the data word to be written into the addressed memory location. The 24XX08 acknowledges again and the master generates a STOP condition. This initiates the internal write cycle and, during this time, the 24XX08 will not generate Acknowledge signals (Figure 4-1).

4.2   Page Write

The write-control byte, word address and the first data byte are transmitted to the 24XX08 in the same way as in a byte write. However, instead of generating a STOP condition, the master transmits up to 16 data bytes to the 24XX08, which are temporarily stored in the on-chip page buffer and will be written into memory once the master has transmitted a STOP condition. Upon receipt of each word, the four lower-order address pointer bits are internally incremented by '1'. The higher-order 7 bits of the word address remain constant. If the master should transmit more than 16 words prior to generating the STOP condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the STOP condition is received an internal write cycle will begin (Figure 4-2).

> **Note:** Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page-size') and end at addresses that are integer multiples of [page size - 1]. If a page write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page, as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

FIGURE 4-1:   BYTE WRITE
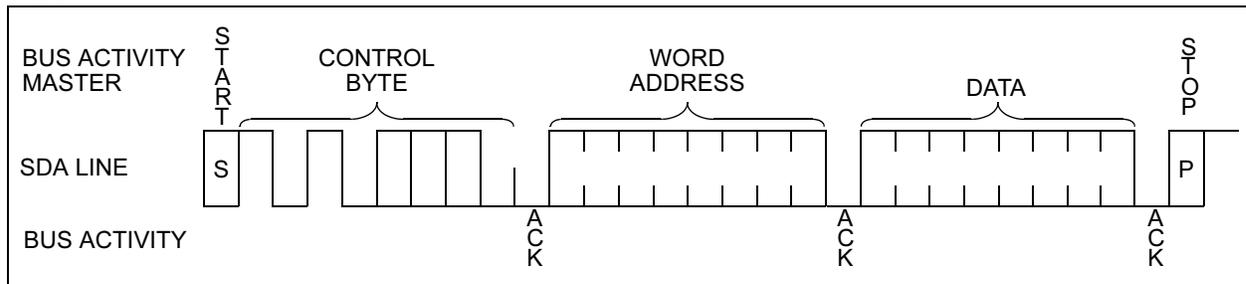
FIGURE 4-2:   PAGE WRITE
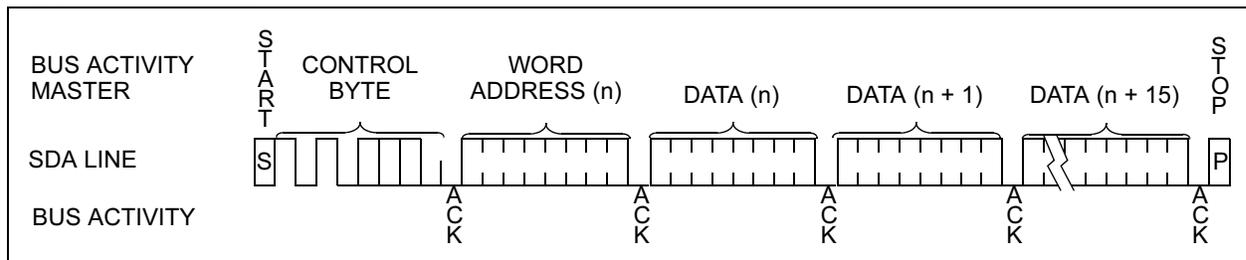
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5.0 ACKNOWLEDGE POLLING

Since the device will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the STOP condition for a Write command has been issued from the master, the device initiates the internally-timed write cycle and ACK polling can then be initiated immediately. This involves the master sending a START condition followed by the control byte for a Write command (R/$\overline{W}$ = 0). If the device is still busy with the write cycle, no ACK will be returned. If the cycle is complete, the device will return the ACK and the master can then proceed with the next Read or Write command. See Figure 5-1 for a flow diagram of this operation.

FIGURE 5-1: ACKNOWLEDGE POLLING FLOW

6.0 WRITE PROTECTION

The 24XX08 can be used as a serial ROM when the WP pin is connected to VCC. Programming will be inhibited and the entire memory will be write protected.
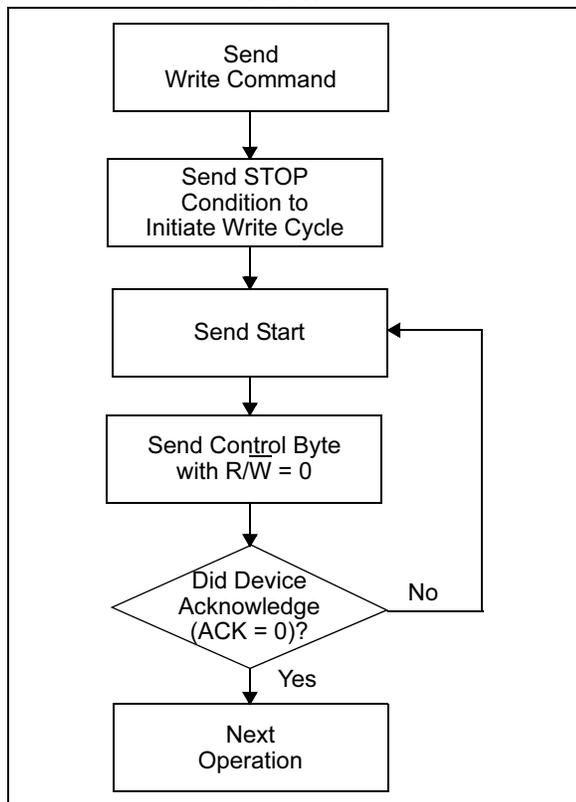
7.0   READ OPERATION

Read operations are initiated in the same way as write operations, with the exception that the R/$\overline{W}$ bit of the slave address is set to '1'. There are three basic types of read operations: current address read, random read and sequential read.

7.1   Current Address Read

The 24XX08 contains an address counter that maintains the address of the last word accessed, internally incremented by '1'. Therefore, if the previous access (either a read or write operation) was to address n, the next current address read operation would access data from address n + 1. Upon receipt of the slave address with R/$\overline{W}$ bit set to '1', the 24XX08 issues an acknowledge and transmits the 8-bit data word. The master will not acknowledge the transfer but does generate a STOP condition and the 24XX08 discontinues transmission (Figure 7-1).

7.2   Random Read

Random read operations allow the master to access any memory location in a random manner. To perform this type of read operation, the word address must first be set. This is accomplished by sending the word address to the 24XX08 as part of a write operation. Once the word address is sent, the master generates a START condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. The master then issues the control byte again, but with the R/$\overline{W}$ bit set to a '1'. The 24XX08 will then issue an acknowledge and transmit the 8-bit data word. The master will not acknowledge the transfer but does generate a STOP condition and the 24XX08 will discontinue transmission (Figure 7-2).

7.3   Sequential Read

Sequential reads are initiated in the same way as a random read, except that once the 24XX08 transmits the first data byte, the master issues an acknowledge as opposed to a STOP condition in a random read. This directs the 24XX08 to transmit the next sequentially-addressed 8-bit word (Figure 7-3).

To provide sequential reads, the 24XX08 contains an internal address pointer that is incremented by one upon completion of each operation. This address pointer allows the entire memory contents to be serially read during one operation.

7.4   Noise Protection

The 24XX08 employs a Vcc threshold detector circuit which disables the internal erase/write logic if the Vcc is below 1.5V at nominal conditions.

The SCL and SDA inputs have Schmitt Trigger and filter circuits which suppress noise spikes to assure proper device operation, even on a noisy bus.

FIGURE 7-1:   CURRENT ADDRESS READ
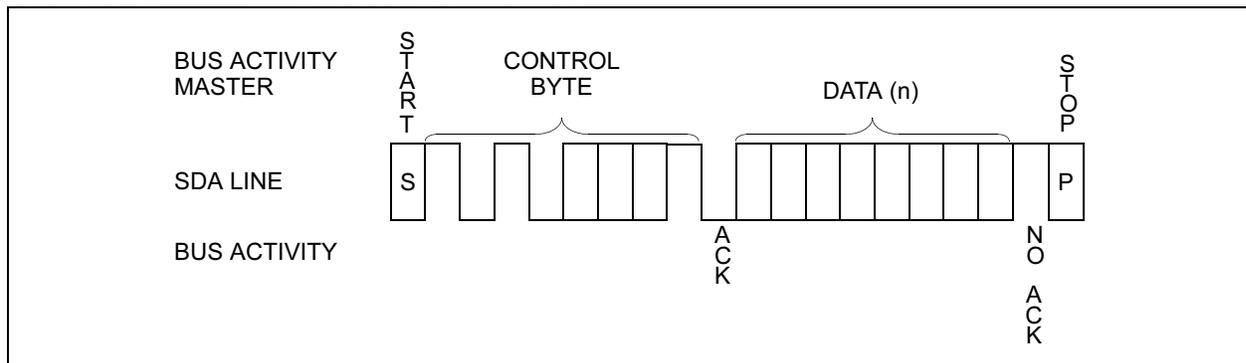
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FIGURE 7-2: **RANDOM READ**
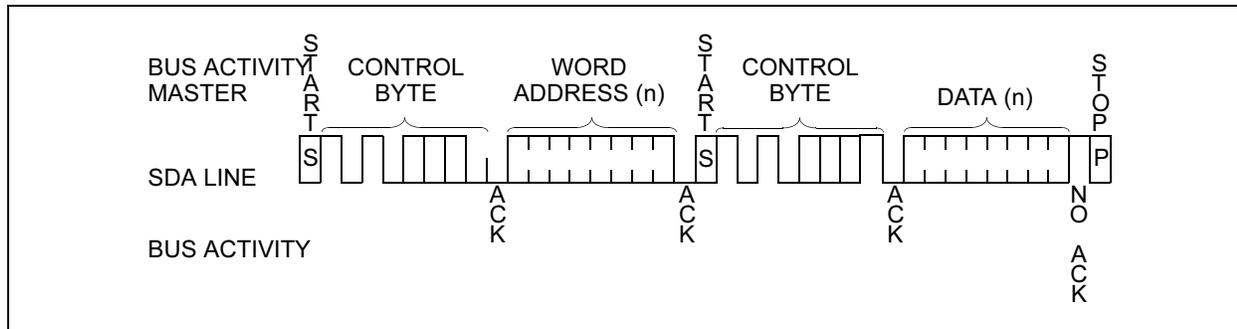
FIGURE 7-3: **SEQUENTIAL READ**
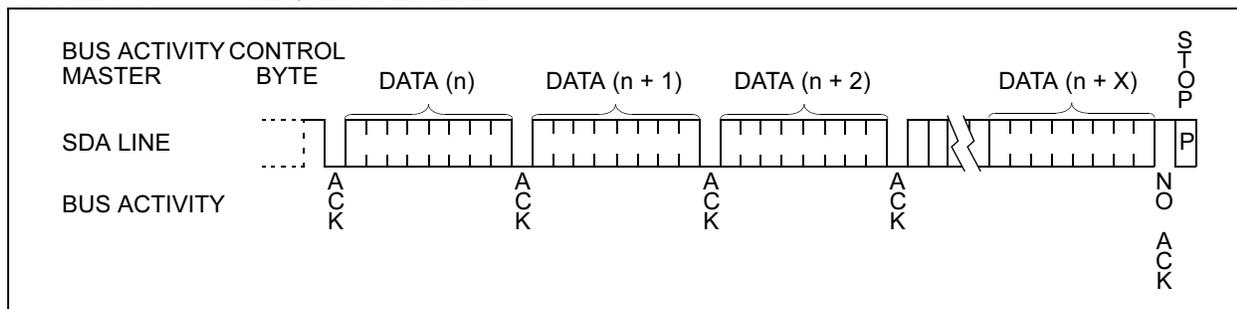
8.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 8-1.

TABLE 8-1: PIN FUNCTION TABLE

Name	PDIP	SOIC	TSSOP	MSOP	SOT-23	Description
A0	1	1	1	1	—	Not Connected
A1	2	2	2	2	—	Not Connected
A2	3	3	3	3	—	Not Connected
Vss	4	4	4	4	2	Ground
SDA	5	5	5	5	3	Serial Address/Data I/O
SCL	6	6	6	6	1	Serial Clock
WP	7	7	7	7	5	Write Protect Input
Vcc	8	8	8	8	4	+1.8V to 5.5V Power Supply

8.1 Serial Address/Data Input/Output (SDA)

SDA is a bi-directional pin used to transfer addresses and data into and out of the device. Since it is an open-drain terminal, the SDA bus requires a pull-up resistor to Vcc (typical 10 kΩ for 100 kHz, 2 kΩ for 400 kHz).

For normal data transfer, SDA is allowed to change only during SCL LOW. Changes during SCL HIGH are reserved for indicating START and STOP conditions.

8.2 Serial Clock (SCL)

The SCL input is used to synchronize the data transfer to and from the device.

8.3 Write Protect (WP)

The WP pin must be connected to either Vss or Vcc.

If tied to Vss, normal memory operation is enabled (read/write the entire memory `00-03FFH`).

If tied to Vcc, WRITE operations are inhibited. The entire memory will be write protected. Read operations are not affected.

This feature allows the user to use the 24XX08 as a serial ROM when WP is enabled (tied to Vcc).

8.4 A0, A1, A2

The A0, A1 and A2 pins are not used by the 24XX08. They may be left floating or tied to either Vss or Vcc.

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9.0   PACKAGING INFORMATION

9.1   Package Marking Information

8-Lead PDIP (300 mil)
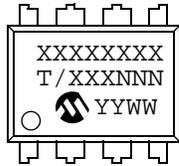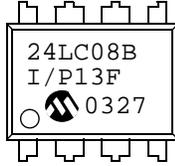
```
XXXXXXXX
T/XXXNNN
○  Ⓜ YYWW
```

Example:

```
24LC08B
I/P13F
○  Ⓜ 0327
```

8-Lead SOIC (150 mil)

```
XXXXXXXX
T/XXYYWW
○  Ⓜ  NNN
```

Example:

```
24LC08B
I/SN0327
○  Ⓜ 13F
```

8-Lead TSSOP

```
○   XXXX
    TYWW
Ⓜ   NNN
```

Example:

```
○    4L08
    I327
Ⓜ   13F
```
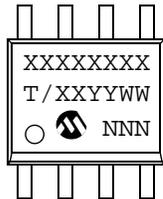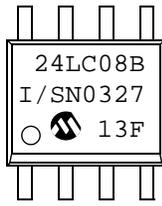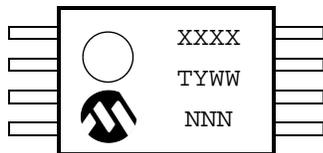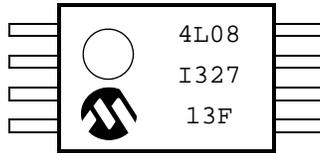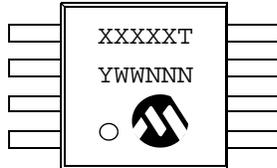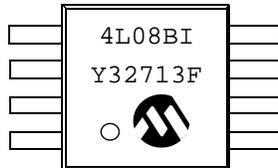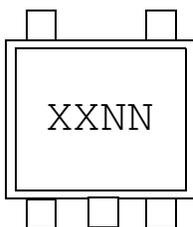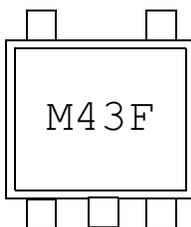
Device	TSSOP/MSOP Marking Codes	
	STD	Pb-free
24AA08	4A08	G4A8
24LC08B	4L8B	G4L8

8-Lead MSOP

```
XXXXXT
YWWNNN
○  Ⓜ
```

Example:

```
4L08BI
Y32713F
○  Ⓜ
```

5-Lead SOT-23

```
XXNN
```

Example:

```
M43F
```

Device	SOT-23 Marking Codes	
	STD	Pb-free
24AA08	B4	B4
24LC08B-I	M4	M4
24LC08B-E	N4	N4
Note: Pb-free part number using "G" suffix is marked on carton		

Legend:	XX...X	Customer specific information*
	T	Temperature grade (I, E)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

*Standard OTP marking consists of Microchip part number, year code, week code, and traceability code.

## 8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)
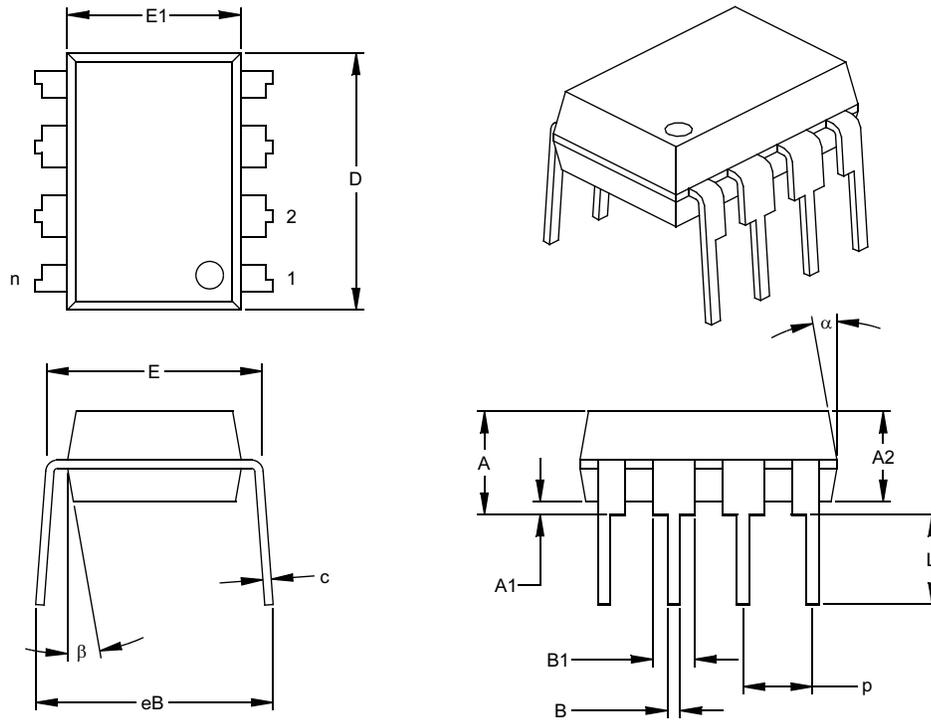
	Units	INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed
.010" (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-018

24AA08/24LC08B

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)
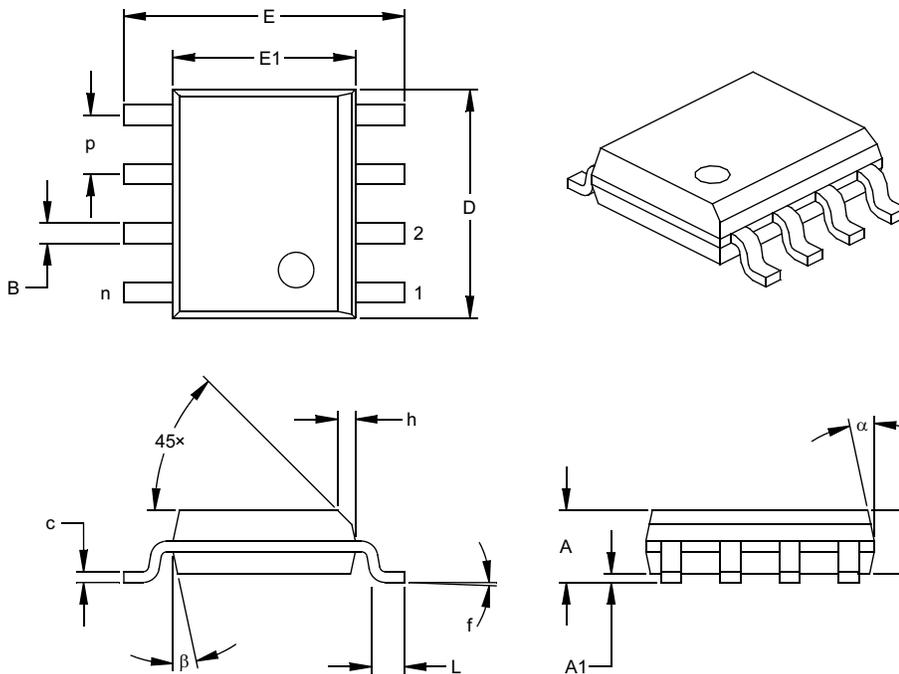
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Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	f	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed
.010" (0.254mm) per side.
JEDEC Equivalent: MS-012
Drawing No. C04-057

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8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)
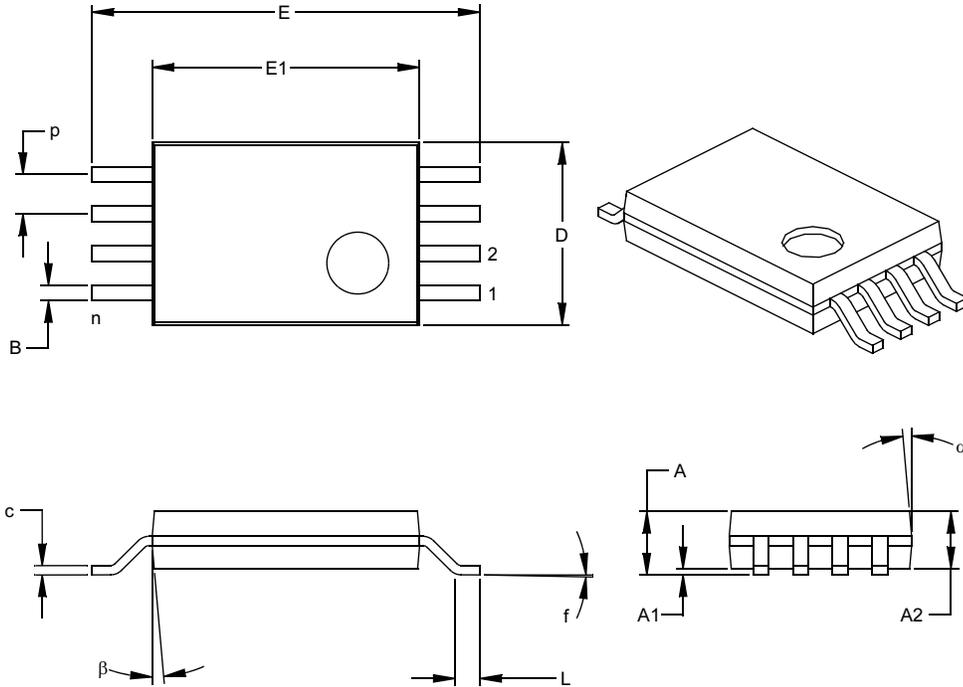
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Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026			0.65	
Overall Height	A			.043			1.10
Molded Package Thickness	A2	.033	.035	.037	0.85	0.90	0.95
Standoff §	A1	.002	.004	.006	0.05	0.10	0.15
Overall Width	E	.246	.251	.256	6.25	6.38	6.50
Molded Package Width	E1	.169	.173	.177	4.30	4.40	4.50
Molded Package Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.020	.024	.028	0.50	0.60	0.70
Foot Angle	f	0	4	8	0	4	8
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.010	.012	0.19	0.25	0.30
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed
.005" (0.127mm) per side.
JEDEC Equivalent: MO-153
Drawing No. C04-086

24AA08/24LC08B

8-Lead Plastic Micro Small Outline Package (MSOP)
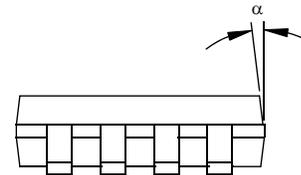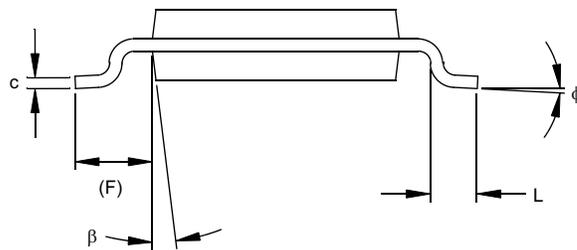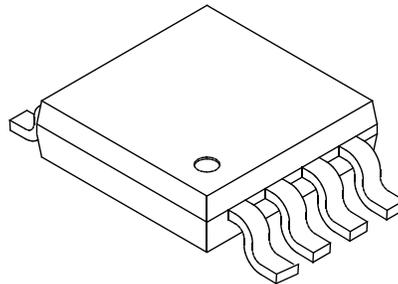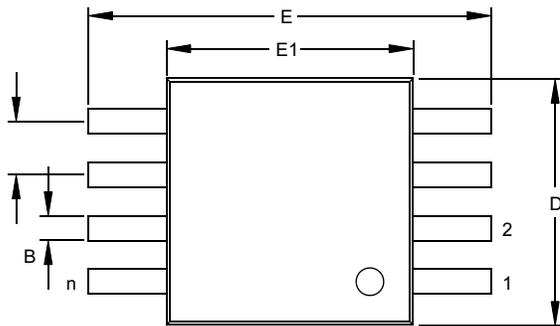
	Units		INCHES			MILLIMETERS*	
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8				8
Pitch	p		.026			0.65	
Overall Height	A			.044			1.18
Molded Package Thickness	A2	.030	.034	.038	0.76	0.86	0.97
Standoff §	A1	.002		.006	0.05		0.15
Overall Width	E	.184	.193	.200	4.67	4.90	.5.08
Molded Package Width	E1	.114	.118	.122	2.90	3.00	3.10
Overall Length	D	.114	.118	.122	2.90	3.00	3.10
Foot Length	L	.016	.022	.028	0.40	0.55	0.70
Footprint (Reference)	F	.035	.037	.039	0.90	0.95	1.00
Foot Angle	φ	0		6	0		6
Lead Thickness	c	.004	.006	.008	0.10	0.15	0.20
Lead Width	B	.010	.012	.016	0.25	0.30	0.40
Mold Draft Angle Top	α		7			7	
Mold Draft Angle Bottom	β		7			7	

*Controlling Parameter
§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
Drawing No. C04-111

5-Lead Plastic Small Outline Transistor (OT) (SOT-23)
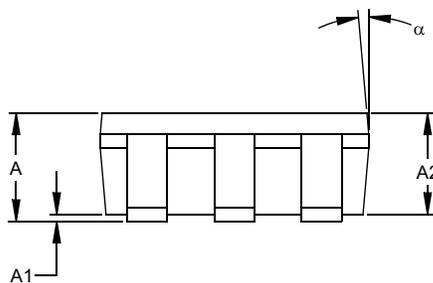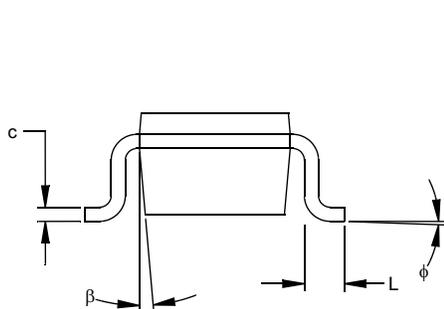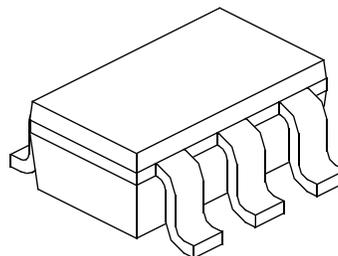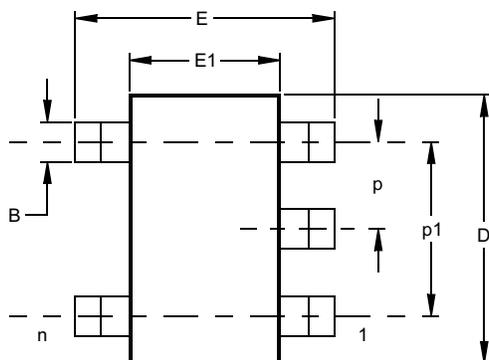
	Units	INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		5			5	
Pitch	p		.038			0.95	
Outside lead pitch (basic)	p1		.075			1.90	
Overall Height	A	.035	.046	.057	0.90	1.18	1.45
Molded Package Thickness	A2	.035	.043	.051	0.90	1.10	1.30
Standoff §	A1	.000	.003	.006	0.00	0.08	0.15
Overall Width	E	.102	.110	.118	2.60	2.80	3.00
Molded Package Width	E1	.059	.064	.069	1.50	1.63	1.75
Overall Length	D	.110	.116	.122	2.80	2.95	3.10
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.014	.017	.020	0.35	0.43	0.50
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed
.010" (0.254mm) per side.
JEDEC Equivalent: MO-178
Drawing No. C04-091

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	X
Device	Temperature Range	Package	Lead Finish

24AA08: = 1.8V, 16 Kbit I^{2}C Serial EEPROM
24AA08T: = 1.8V, 16 Kbit I^{2}C Serial EEPROM (Tape and Reel)
24LC08B: = 2.5V, 16 Kbit I^{2}C Serial EEPROM
24LC08BT: = 2.5V, 16 Kbit I^{2}C Serial EEPROM (Tape and Reel)

Temperature Range:
I = -40°C to +85°C
E = -40°C to +125°C

Package:
P = Plastic DIP (300 mil body), 8-lead
SN = Plastic SOIC (150 mil body), 8-lead
ST = Plastic TSSOP (4.4 mm), 8-lead
MS = Plastic Micro Small Outline (MSOP), 8-lead
OT = SOT-23, 5-lead (Tape and Reel only)

Lead Finish
Blank = Standard 63% / 37% SnPb
G = Matte Tin (Pure Sn)

Examples:

a) 24AA08-I/P: Industrial Temperature,1.8V, PDIP package
b) 24AA08-I/SN: Industrial Temperature,1.8V, SOIC package
c) 24AA08T-I/OT: Industrial Temperature, 1.8V, SOT-23 package, Tape and Reel
d) 24LC08B-I/P: Industrial Temperature, 2.5V, PDIP package
e) 24LC08B-E/SN: Automotive Temp.,2.5V SOIC package
f) 24LC08BT-I/OT: Industrial Temperature, 2.5V, SOT-23 package, Tape and Reel
g) 24LC08B-I/PG: Industrial Temperature, 2.5V, PDIP package, Pb-free
h) 24LC08BT-I/SNG: Industrial Temperature, 2.5V, SOIC package, Tape and Reel, Pb-free

Sales and Support

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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NOTES:

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.

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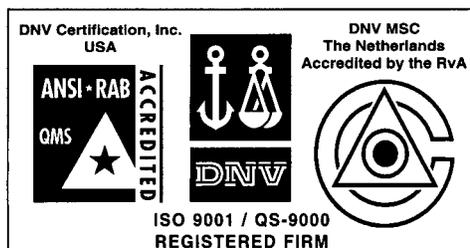
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Tel: 480-792-7200 Fax: 480-792-7277
Technical Support: 480-792-7627
Web Address: http://www.microchip.com

Atlanta
3780 Mansell Road, Suite 130
Alpharetta, GA 30022
Tel: 770-640-0034 Fax: 770-640-0307

Boston
2 Lan Drive, Suite 120
Westford, MA 01886
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Dallas
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Detroit
Tri-Atria Office Building
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Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Kokomo
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Kokomo, IN 46902
Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles
18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

Phoenix
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7966 Fax: 480-792-4338

San Jose
Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto
6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia
Microchip Technology Australia Pty Ltd
Marketing Support Division
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing
Microchip Technology Consulting (Shanghai)
Co., Ltd., Beijing Liaison Office
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu
Microchip Technology Consulting (Shanghai)
Co., Ltd., Chengdu Liaison Office
Rm. 2401-2402, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-86766200 Fax: 86-28-86766599

China - Fuzhou
Microchip Technology Consulting (Shanghai)
Co., Ltd., Fuzhou Liaison Office
Unit 28F, World Trade Plaza
No. 71 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7503506 Fax: 86-591-7503521

China - Hong Kong SAR
Microchip Technology Hongkong Ltd.
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

China - Shanghai
Microchip Technology Consulting (Shanghai)
Co., Ltd.
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen
Microchip Technology Consulting (Shanghai)
Co., Ltd., Shenzhen Liaison Office
Rm. 1812, 18/F, Building A, United Plaza
No. 5022 Binhe Road, Futian District
Shenzhen 518033, China
Tel: 86-755-82901380 Fax: 86-755-8295-1393

China - Qingdao
Rm. B505A, Fullhope Plaza,
No. 12 Hong Kong Central Rd.
Qingdao 266071, China
Tel: 86-532-5027355 Fax: 86-532-5027205

India
Microchip Technology Inc.
India Liaison Office
Marketing Support Division
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaugnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan
Microchip Technology Japan K.K.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea
Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Singapore
Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan
Microchip Technology (Barbados) Inc.,
Taiwan Branch
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Austria
Microchip Technology Austria GmbH
Durisolstrasse 2
A-4600 Wels
Austria
Tel: 43-7242-2244-399
Fax: 43-7242-2244-393

Denmark
Microchip Technology Nordic ApS
Regus Business Centre
Lautrup hoj 1-3
Ballerup DK-2750 Denmark
Tel: 45-4420-9895 Fax: 45-4420-9910

France
Microchip Technology SARL
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - ler Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany
Microchip Technology GmbH
Steinheilstrasse 10
D-85737 Ismaning, Germany
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy
Microchip Technology SRL
Via Quasimodo, 12
20025 Legnano (MI)
Milan, Italy
Tel: 39-0331-742611 Fax: 39-0331-466781

United Kingdom
Microchip Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44-118-921-5869 Fax: 44-118-921-5820

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